Arisentec

FLEX PCB

CAPABILITIES

Layers	1 - 12L	Outline (Laser) Tolerance	±2 mil
Max Board Size	15.75″ x 23.5″	Cover Layer Dams	8 mil
Max Board Thickness	.040″ without stiffener	Flammability	94V-0
Min. Board Thickness	4 mil	Impedance Control	≤50 OHMS = ±5 OHMS >50 OHMS = ±10%
Min. Line Width	2.5 mil		
Min. Line Space	2.5 mil		
Min. Mechanical Drill	4 mil		

* Dynamic Flex & Flex-to-Install

SURFACE FINISHES

- HASL
- ENIG
- ENEPIG
- Immersion Silver
- Immersion Tin
- Electrolytic Nickel/Gold
- Wire Bondable Soft Gold
- OSP

MATERIALS

- Polyimide (adhesive, adhesiveless)
- PET/Polyester
- FR4/Polyimide/thick film stiffeners
- Material thickness:
  .5 mil through 2 mil

CERTIFICATIONS

- UL
- ISO9001 (Quality System)
- IATF16949 (Automotive)
- ISO13485 (Medical)
- AS9100 (Aerospace)
- ISO14001 (Environmental)
- OHSAS18001 (Safety)
- ISO27001 (IP Protection)

LEAD TIMES

Quick Turn, 5 - 10 Days from Asia
High Mix Low Volume
Medium to High Volume
* Technology level dependent

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